

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc6804hg-2#pbf

(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.361296**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.012786	1000000	35389.2734375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.133910	962000	370638		
		Iron (Fe)	7439-89-6	0.000000	0	0		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.004176	30000	11558.3925781		
		Silicon (Si)	7440-21-3	0.000905	1500	578.473205566		
		Magnesium (Mg)	7439-95-4	0.000209	1500	578.473205566		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.139200</b>	<b>1000000</b>	<b>385279.78125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012701	1000000	35153.8046875		
		<b>External Plating Total:</b>				<b>0.012701</b>	<b>1000000</b>	<b>35153.8046875</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001114	1000000	3083.34521484		
<b>Internal Plating Total:</b>				<b>0.001114</b>	<b>1000000</b>	<b>3083.34521484</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.002611	750000	7226.76318359		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000870	250000	2407.99853516		
<b>Die Attach Total:</b>				<b>0.003481</b>	<b>1000000</b>	<b>9634.76171875</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.019673	103000	54451.2070312		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.170945	895000	473144.03125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000382	2000	1057.30505371		
		<b>Encapsulation Total:</b>				<b>0.191000</b>	<b>1000000</b>	<b>528652.5625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.001014	1000000	2806.56396484		
					<b>TOTAL MASS (g) :</b>	<b>0.361296</b>		